



## Material Content Data Sheet



<b>Sales Product Name</b>		IDD09SG60C		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000809454							
<b>Package</b>		PG-TO252-3-311		<b>Weight*</b>		312.16 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.131	0.04		420		
	non noble metal	tin	7440-31-5	0.034	0.01		108		
	inorganic material	silicon	7440-21-3	1.670	0.53	0.58	5349	5877	
leadframe	non noble metal	iron	7439-89-6	0.162	0.05		521		
	inorganic material	phosphorus	7723-14-0	0.049	0.02		156		
	non noble metal	copper	7440-50-8	162.275	51.99	52.06	519847	520523	
wire	non noble metal	aluminium	7429-90-5	0.905	0.29	0.29	2899	2899	
encapsulation	organic material	carbon black	1333-86-4	1.431	0.46		4584		
	plastics	epoxy resin	-	25.044	8.02		80227		
	inorganic material	silicondioxide	60676-86-0	116.632	37.36	45.84	373630	458442	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.20	1.20	11981	11981	
plating	non noble metal	nickel	7440-02-0	0.086	0.03		277		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	278	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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